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Date: 18 April 2001

By:



Vladimir Skliba

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of Hui WANG

Serial No.: Unassigned

Examiner: Unassigned

Filed: Herewith

Art Unit: Unassigned

For: PLATING APPARATUS AND METHOD

Commissioner for Patents
Washington, D.C. 20231

INFORMATION DISCLOSURE STATEMENT TRANSMITTAL

Enclosed is an Information Disclosure Statement and accompanying Form PTO/SB/08 for the above-identified patent application.

- In accordance with 37 C.F.R. §1.97(b), no additional fee for submission of the IDS is required.
- In accordance with 37 C.F.R. §1.97(c), also enclosed is:
- the fee of \$180.00 as set forth in 37 C.F.R. §1.17(p); or
- a statement as specified in 37 C.F.R. §1.97(e).
- In accordance with 37 C.F.R. §1.97(d), a statement as specified in 37 C.F.R. § 1.97(e) and the fee of \$180.00 as set forth in 37 C.F.R. §1.17(p) are also enclosed.
- Check No. _____ in the amount of \$ ____ for the total fee is attached.
- Please charge \$ ____ to Deposit Account No. 03-3117 for the total fee.
This paper is being submitted in duplicate.

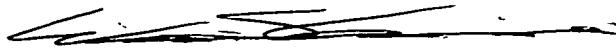
The Commissioner is hereby authorized to charge any appropriate fees under 37 C.F.R. §§1.16, 1.17, and 1.21 that may be required by this paper, and to credit any overpayment, to Deposit Account No. 03-3117.

Dated: 4-17-01

Cooley Godward LLP
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Respectfully submitted,
COOLEY GODWARD LLP



William S. Galliani
Reg. No. 33,885

SAC
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10-10-01
PATENT

Attorney Docket No. ACMR-001/02US

Express Mail Label Number: EL514032537US
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Date: 18 April 2001

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Vladimir Skiba

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of Hui WANG
Serial No.: 09/837902
Filed: 4-18-01

Examiner: Unassigned *Leader*
Art Unit: Unassigned *1741*

For: PLATING APPARATUS AND METHOD

Commissioner for Patents
Washington, D.C. 20231

**INFORMATION DISCLOSURE STATEMENT
UNDER 37 C.F.R. §1.97(b)**

In accordance with the duty of disclosure set forth in 37 C.F.R. §1.56, Applicant(s) hereby submits the following information in conformance with 37 C.F.R. §§1.97 and 1.98.

- [] Pursuant to 37 C.F.R. §1.98, a copy of each document cited in the attached Form PTO/SB/08 is enclosed.
- [X] No copies of the publications listed on the attached Form PTO/SB/08 are being provided pursuant to 37 C.F.R. §1.98(d) because the publications were previously cited by or submitted to the Office in prior Application Serial No. 09/232,864 to which the above-identified application claims priority under 35 U.S.C. §120.
- [] Publication(s) _____ listed on the attached Form PTO/SB/08 were cited in a foreign search or examination report corresponding to _____ application serial no. _____ and mailed on _____.

- [] Enclosed is a copy of a non-English publication(s) _____. Pursuant to §609 of the M.P.E.P., Applicant submits the attached foreign search or examination report, which cites such non-English language publication(s).
- [] Enclosed is a copy of a non-English publication(s) _____. English language publication _____ (copy enclosed) claims priority from this non-English publication.
- [] Enclosed is an explanation of non-English publication(s) _____ for which an English translation is not available.
- [] Enclosed is an English translation of the non-English publication(s) cited in the attached Form PTO/SB/08.
- [] Enclosed is a copy of pending patent Application Serial No. _____.

This Information Disclosure Statement is filed within any one of the following time periods:

- [X] within three months from the filing date of this national application other than a CPA under 37 C.F.R. § 1.53(d);
- [] within three months from the date of entry of the national stage as set forth in 37 C.F.R. § 1.491 in this international application;
- [] before the mailing date of a first office action on the merits; or
- [] before the mailing of a first office action after the filing of a request for continued examination under 37 C.F.R. § 1.114.

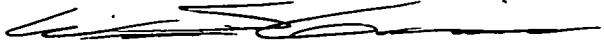
It is respectfully requested that the Examiner consider the above-noted information and return an initialed copy of the attached Form PTO/SB/08 to the undersigned.

Dated: 4-17-01

Respectfully submitted,
COOLEY GODWARD LLP

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Substitute for form 1449A/PTO				<i>Complete if Known</i>	
INFORMATION DISCLOSURE STATEMENT BY APPLICANT <i>(use as many sheets as necessary)</i>				Application Number	Unassigned
				Filing Date	Filed Herewith
				First Named Inventor	Hui WANG
				Group Art Unit	Unassigned
				Examiner Name	Unassigned
Sheet	1	of	2	Attorney Docket Number	ACMR-001/02US

U.S. PATENT DOCUMENTS

FOREIGN PATENT DOCUMENTS

Examiner Signature		Date Considered	
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*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

¹ Unique citation designation number.

² See attached Kinds of U.S. Patent Documents.

³ Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3).

For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document.

⁵ Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST. 16 if possible.

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Sheet	2	of	2	Attorney Docket Number	ACMR-001/02US



OTHER PRIOR ART – NON PATENT LITERATURE DOCUMENTS				
Examiner Initials*	Cite No. ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.		T ²
	D1	PATENT ABSTRACT OF JAPAN, "Plating Method," Publication No. 57171690, Publication Date: Oct. 22, 1982		
	D2	PATENT ABSTRACT OF JAPAN, "Partial Plating Device," Publication No. 01234590, Publication Date: Sep. 19, 1989		
	D3	CONTOLINI et al., "Copper Electroplating Process for Sub-Half-Micron ULSI Structures," <u>VMIC Conference 1995 ISMIC – 104/95/0322</u> , Pgs. 322-328, Jun. 27-29, 1995		
	D4	DEVARAJ et al., "Pulsed Electrodeposition of Copper," <u>Plating & Surface Finishing</u> , Pgs. 72-78, Aug. 1992		
	D5	DUBIN, "Copper Plating Techniques for ULSI Metallization," <u>Advanced MicroDevices</u>		
	D6	DUBIN, V.M., "Electrochemical Deposition of Copper for On-Chip Interconnects," <u>Advanced MicroDevices</u>		
	D7	GAUVIN et al., "The Effect of Chloride Ions on Copper Deposition," <u>J. of Electrochemical Society</u> , Vol. 99, Pgs. 71-75, Feb. 1952		
	D8	OSERO, N.M., "An Overview of Pulse Plating," <u>Plating and Surface Finishing</u> , Mar. 1986		
	D9	PASSAL, F., "Copper Plating During the Last Fifty Years," <u>Plating</u> , Pgs. 628-638, Jun. 1959		
	D10	SINGER, P., "Copper Goes Mainstream: Low k to Follow," <u>Semiconductor International</u> , Pgs. 67-70, Nov. 1997		

Examiner Signature	Date Considered
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